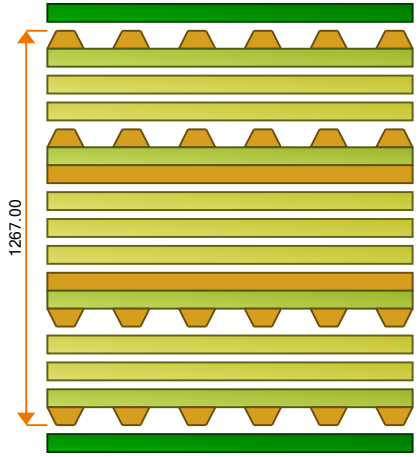

Layer	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	εr	Loss Tangent	Impedance ID
	Liquid PhotoImageable Mask			25.400		4.000	0.0000	
1		Signal	35.000	35.000				
	FR4 Core		200.000	200.000	45.000	4.200	0.0195	
	PrePreg 1080		75.000	75.000	60.000	4.200	0.0195	
	PrePreg 1080		75.000	75.000	60.000	4.200	0.0195	
2		Signal	18.000	18.000				
	FR4 Core		100.000	100.000	53.000	4.200	0.0195	
3		Plane	18.000	18.000				
	PrePreg 1080		75.000	75.000	60.000	4.200	0.0195	
	PrePreg 1080		75.000	75.000	60.000	4.200	0.0195	
	PrePreg 1080		75.000	75.000	60.000	4.200	0.0195	
4		Plane	18.000	18.000				
	FR4 Core		100.000	100.000	53.000	4.200	0.0195	
5		Signal	18.000	18.000				
	PrePreg 1080		75.000	75.000	60.000	4.200	0.0195	
	PrePreg 1080		75.000	75.000	60.000	4.200	0.0195	
	FR4 Core		200.000	200.000	45.000	4.200	0.0195	
6		Signal	35.000	35.000				
	Liquid PhotoImageable Mask			25.400		4.000	0.0000	

Copper Thickness = 142.000 | Dielectric Thickness = 1125.000 | Solder Mask Thickness = 50.800 | Stack Up Thickness = 1267.000 | Stack Up Thickness with Soldermask = 1317.800
Stack Up Cost = 36.00

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Polar Samples	SM/001	Liquid PhotoImageable Mask	SolderMask	500-001	2	0.50	1.00	2	1.00
Polar Samples	CO/017	FR4 Core	FR4	400-017	2	2.00	4.00	2	4.00
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	7	1.00	7.00	7	7.00
Polar Samples	CO/007	FR4 Core	FR4	400-007	2	2.00	4.00	2	4.00
							16.00		16.00

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 16.00 |
Notes

StackName: EPEC Paper Figure 5	Version:	Revision:	Modification:	Date of Revision:	Editor
Date: 18/06/2018	Associated Documents:				
Author: Richard Attrill					
Department: Engineering					
Site: Waterlooville					